- **Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs**

description

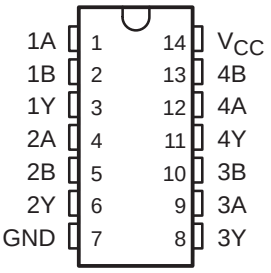
These devices contain four independent 2-input NAND gates. They perform the Boolean functions $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54F00 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74F00 is characterized for operation from 0°C to 70°C.

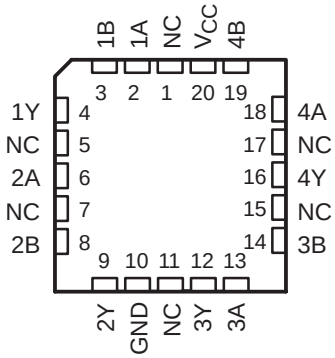
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

SN54F00 . . . J PACKAGE
SN74F00 . . . D OR N PACKAGE
(TOP VIEW)

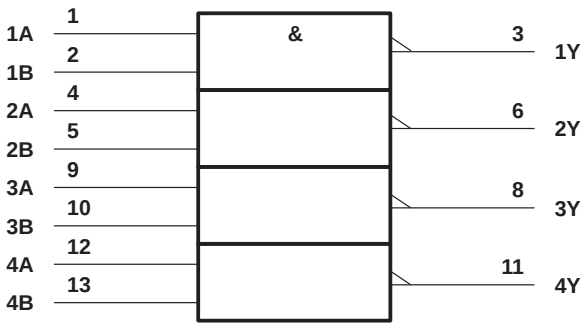


SN54F00 . . . FK PACKAGE
(TOP VIEW)



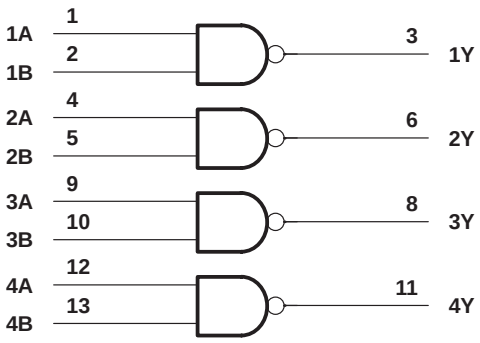
NC – No internal connection

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –1.2 V to 7 V
Input current range . . . . . –30 mA to 5 mA
Voltage range applied to any output in the high state . . . . . –0.5 V to V_{CC}
Current into any output in the low state . . . . . 40 mA
Operating free-air temperature range: SN54F00 . . . . . –55°C to 125°C
SN74F00 . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F00			SN74F00			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			–18			–18	mA
I_{OH}	High-level output current			– 1			– 1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54F00			SN74F00			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA			–1.2			–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = – 1 mA	2.5	3.4		2.5	3.4		V
	V_{CC} = 4.75 V,	I_{OH} = – 1 mA				2.7			
V_{OL}	V_{CC} = 4.5 V,	I_{OL} = 20 mA		0.3	0.5		0.3	0.5	V
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.5 V			– 0.6			– 0.6	mA
I_{OS}§	V_{CC} = 5.5 V,	V_O = 0	–60		–150	–60		–150	mA
I_{CCH}	V_{CC} = 5.5 V,	V_I = 0		1.9	2.8		1.9	2.8	mA
I_{CCL}	V_{CC} = 5.5 V,	V_I = 4.5 V		6.8	10.2		6.8	10.2	mA

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_L = 50 pF, R_L = 500 Ω, T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX†				UNIT
			′F00			SN54F00		SN74F00		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.6	3.3	5	2	7	1.6	6	ns
t_{PHL}			1	2.8	4.3	1.5	6.5	1	5.3	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9757701Q2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701Q2A SNJ54F 00FK
5962-9757701QCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QCA SNJ54F00J
5962-9757701QDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QDA SNJ54F00W
JM38510/33001B2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001B2A
JM38510/33001B2A.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001B2A
JM38510/33001BCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BCA
JM38510/33001BCA.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BCA
JM38510/33001BDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BDA
JM38510/33001BDA.A	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BDA
M38510/33001B2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001B2A
M38510/33001BCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BCA
M38510/33001BDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/33001BDA
SN54F00J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F00J
SN54F00J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54F00J
SN74F00D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	0 to 70	F00
SN74F00DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F00
SN74F00DR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F00

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74F00DRE4	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F00
SN74F00DRG4	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F00
SN74F00N	NRND	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F00N
SN74F00N.A	NRND	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F00N
SN74F00NE4	NRND	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F00N
SN74F00NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F00
SN74F00NSR.A	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F00
SNJ54F00FK	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701Q2A SNJ54F 00FK
SNJ54F00FK.A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701Q2A SNJ54F 00FK
SNJ54F00J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QCA SNJ54F00J
SNJ54F00J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QCA SNJ54F00J
SNJ54F00W	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QDA SNJ54F00W
SNJ54F00W.A	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9757701QDA SNJ54F00W

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54F00, SN74F00 :

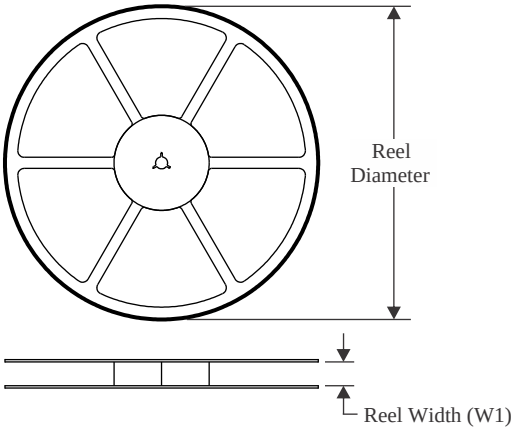
- Catalog : SN74F00
- Military : SN54F00

NOTE: Qualified Version Definitions:

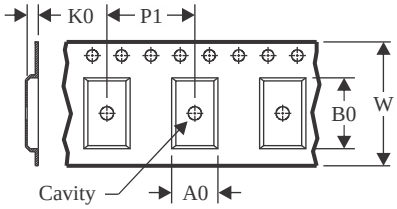
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

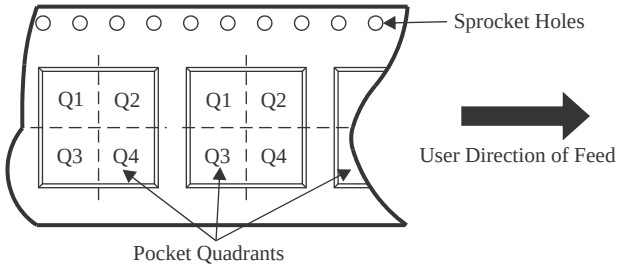


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

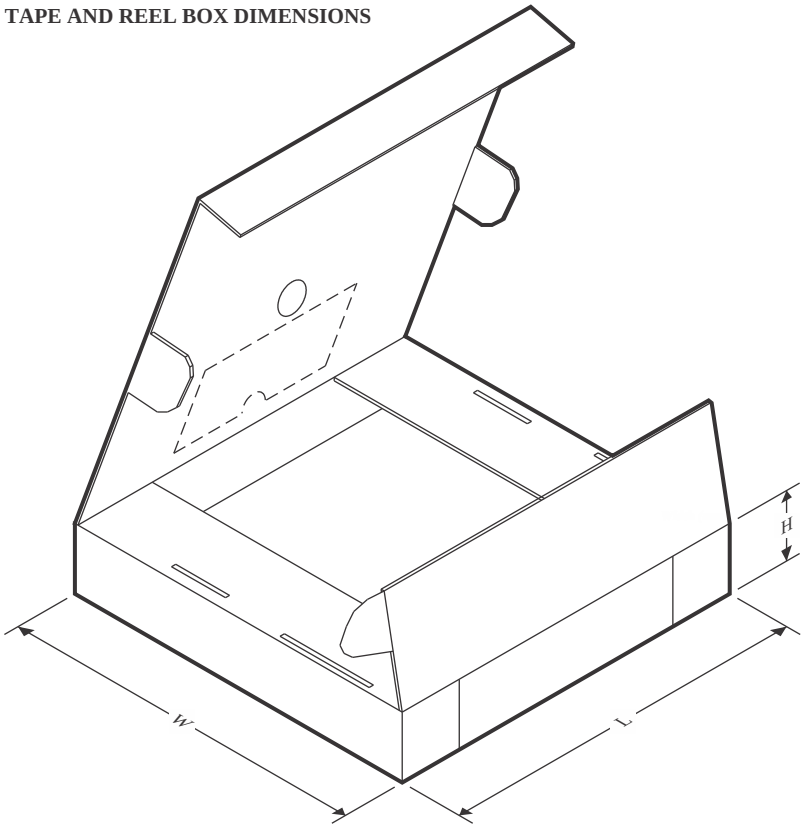
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74F00NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

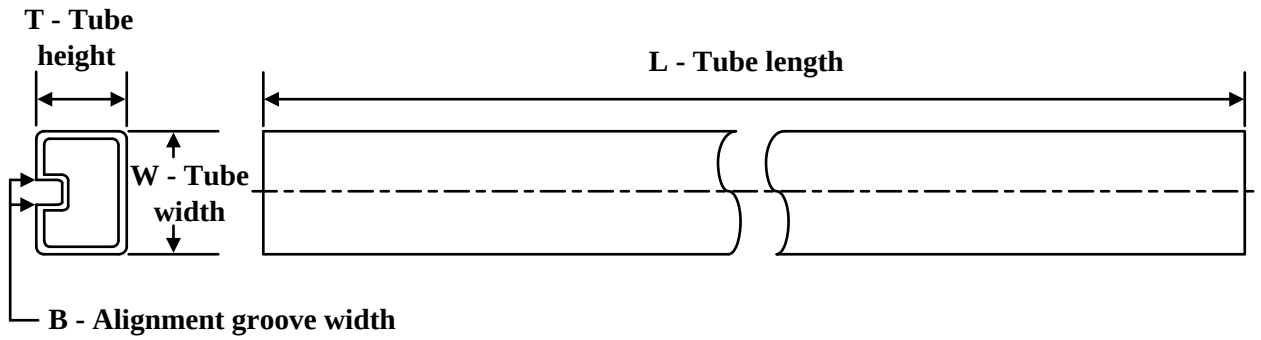
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

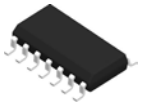
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F00DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74F00NSR	SOP	NS	14	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9757701Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9757701QDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/33001B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/33001B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/33001BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/33001BDA.A	W	CFP	14	25	506.98	26.16	6220	NA
M38510/33001B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/33001BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74F00N	N	PDIP	14	25	506	13.97	11230	4.32
SN74F00N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74F00NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54F00FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F00FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F00W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54F00W.A	W	CFP	14	25	506.98	26.16	6220	NA

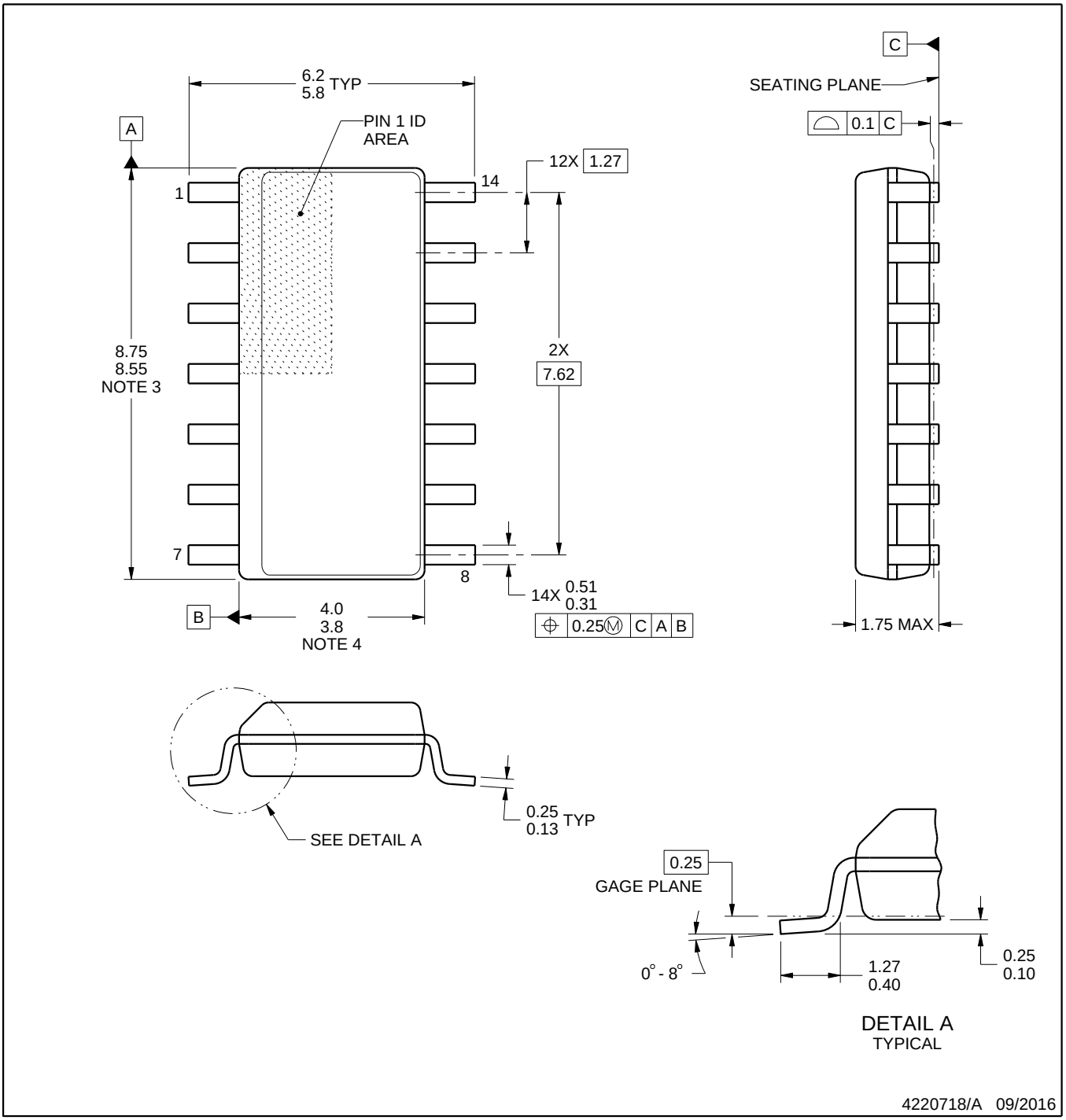


PACKAGE OUTLINE

D0014A

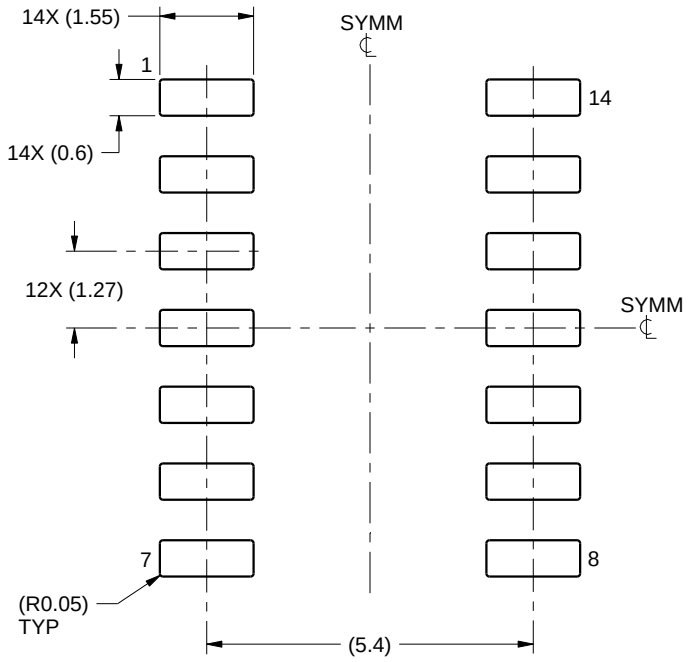
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

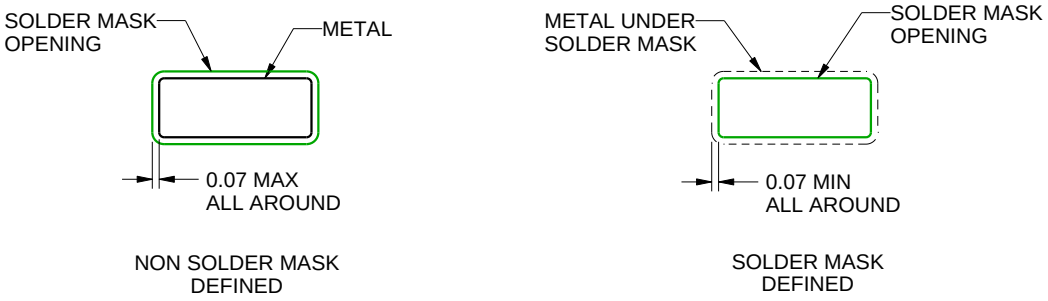


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

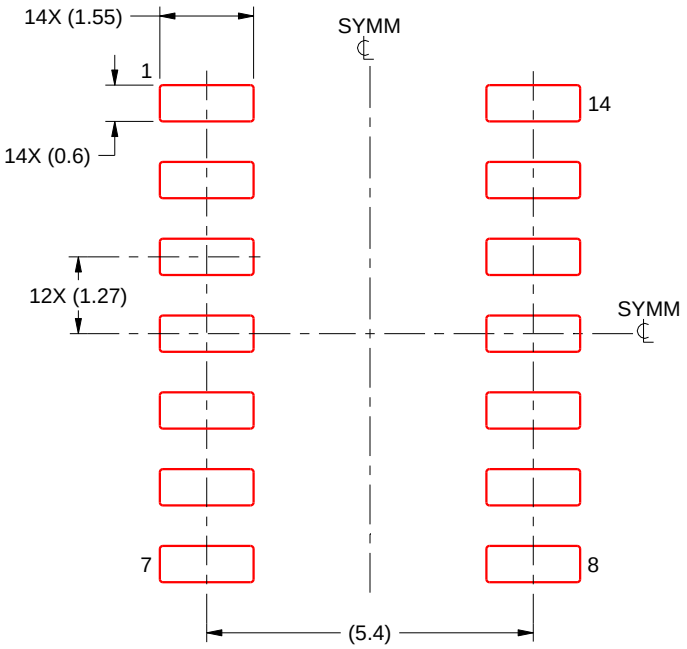
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

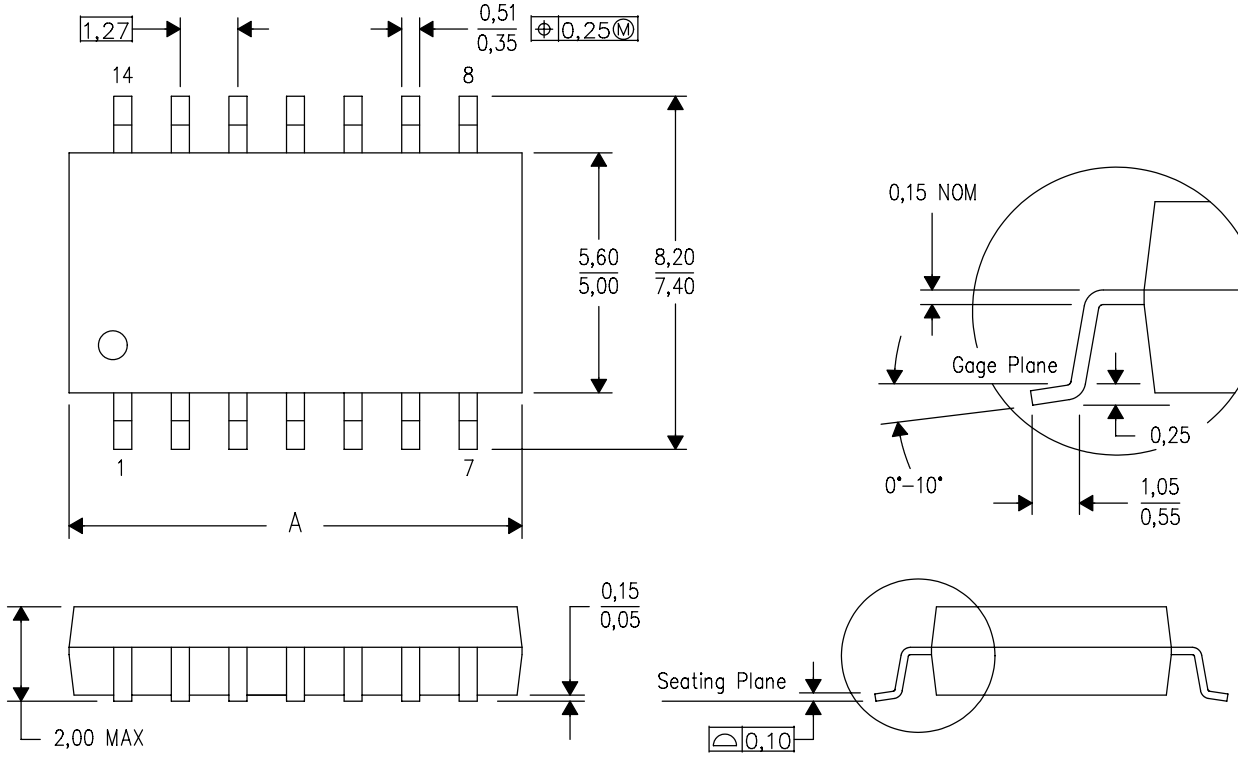
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

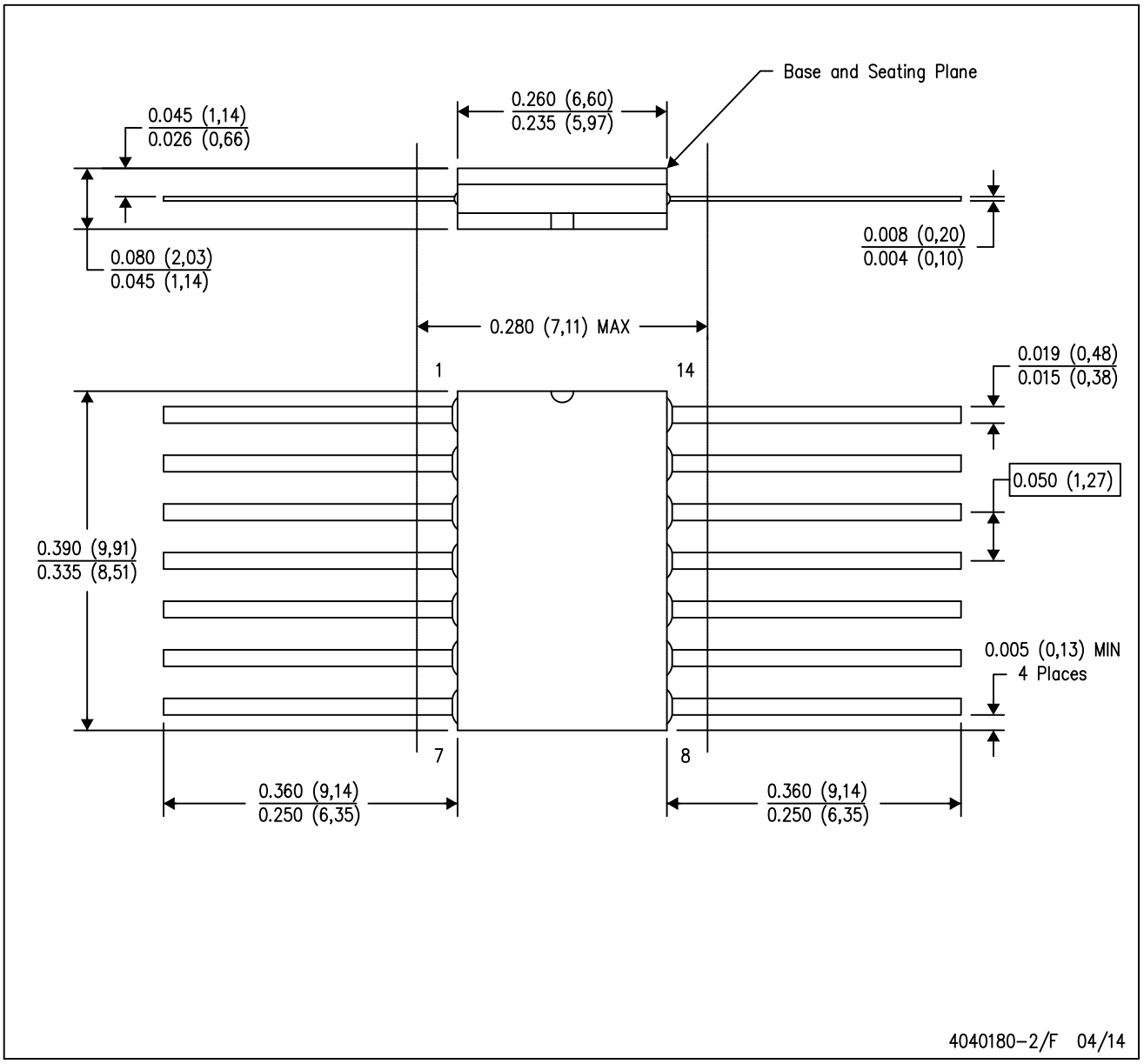


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

GENERIC PACKAGE VIEW

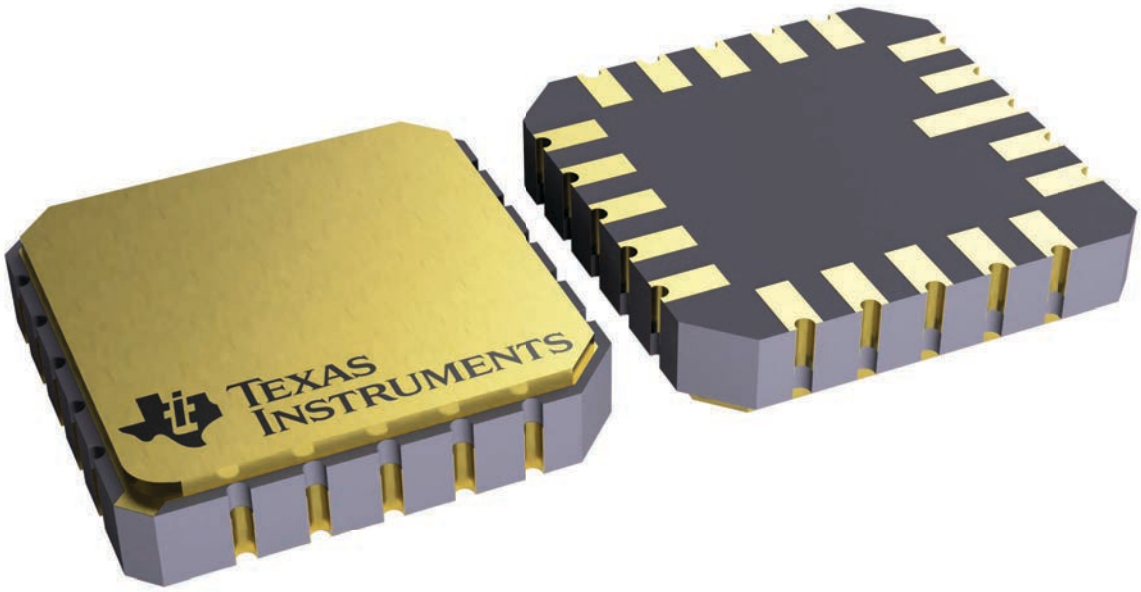
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

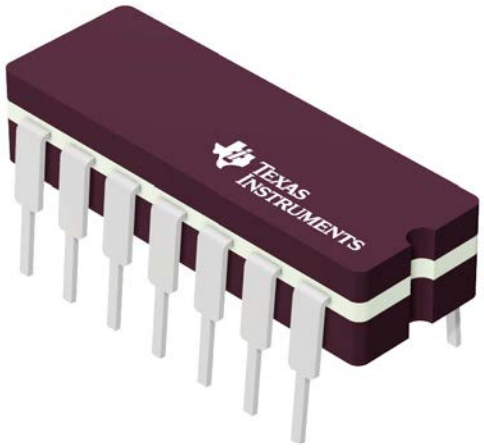


4229370VA\

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

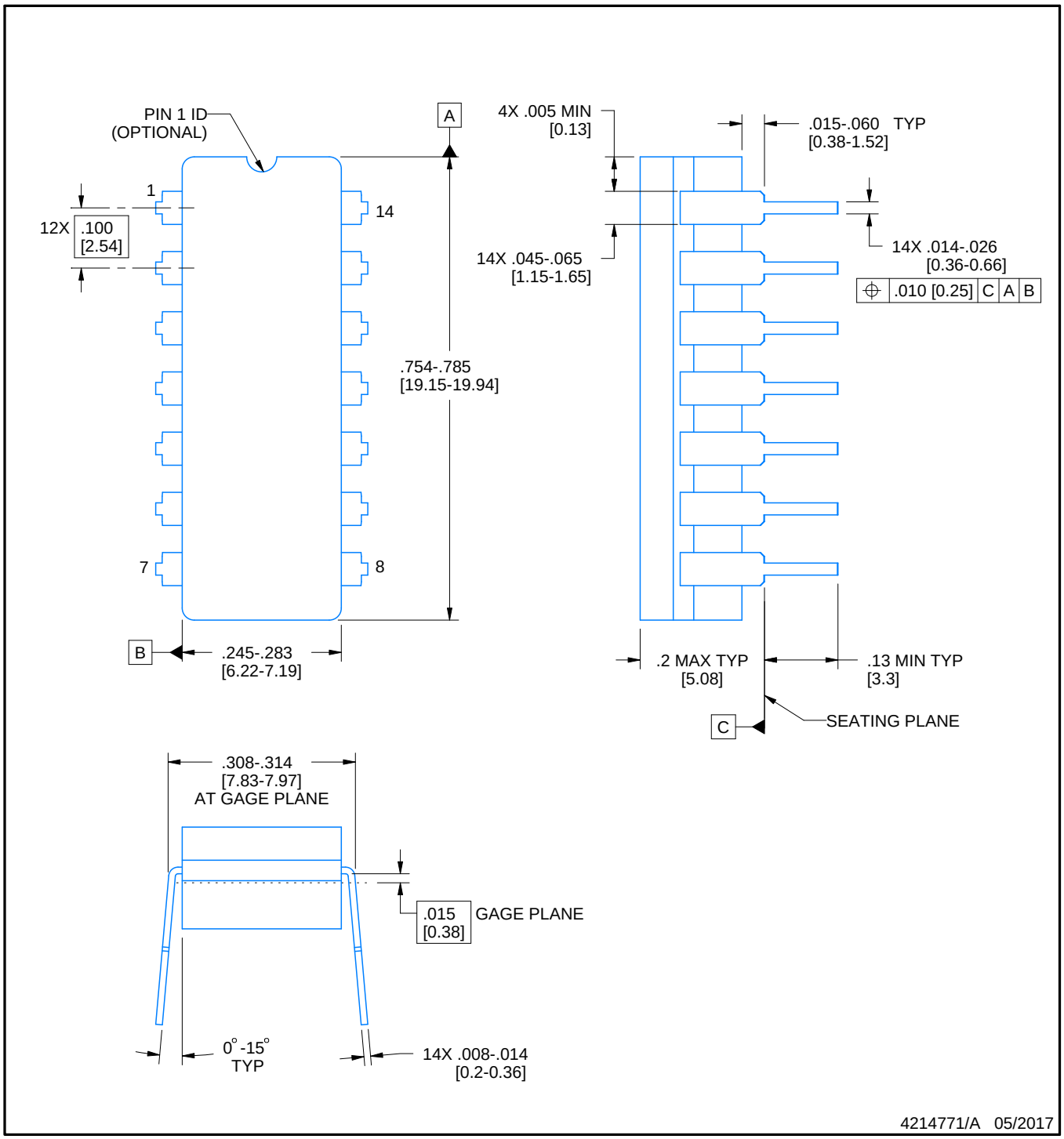


PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

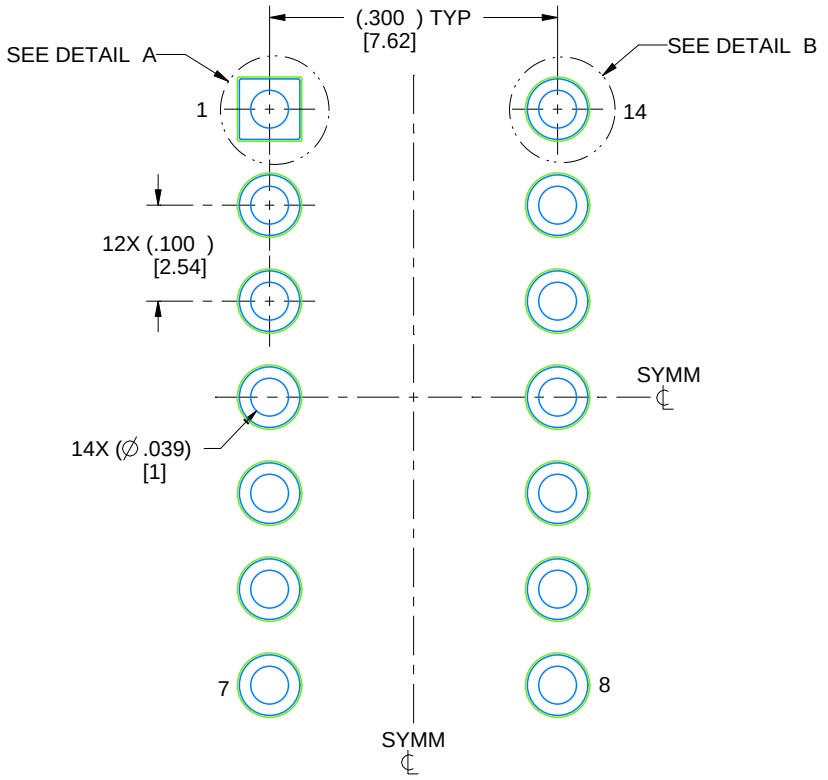
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

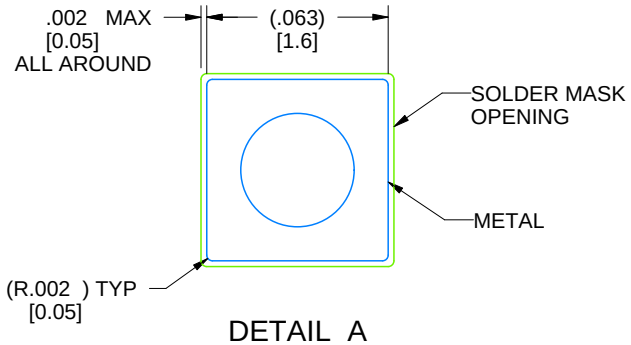
J0014A

CDIP - 5.08 mm max height

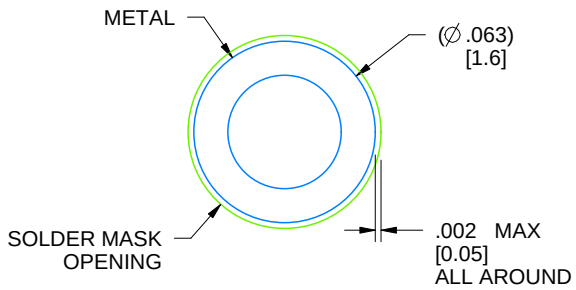
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



DETAIL A
SCALE: 15X



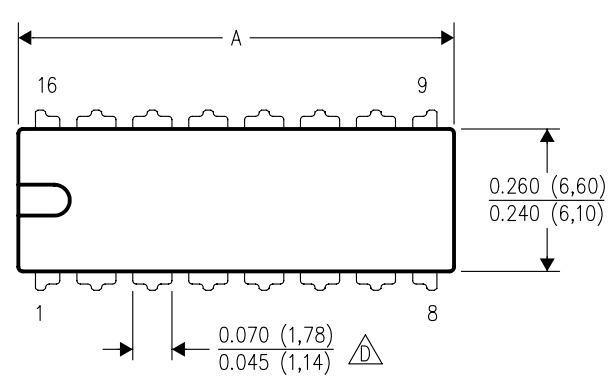
DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

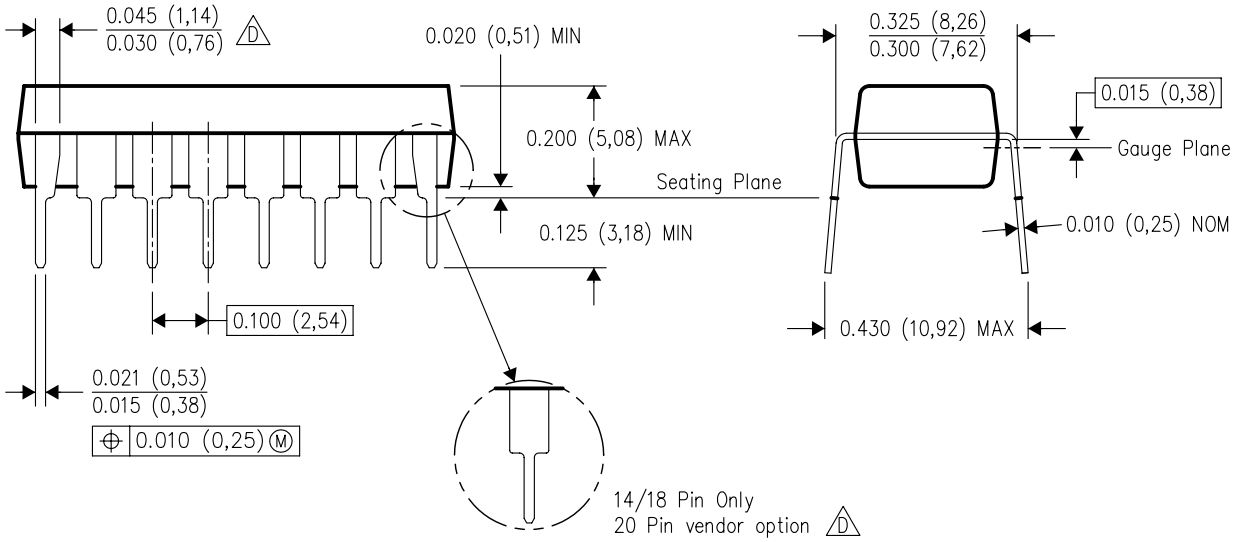
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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